

B1 --This application is a divisional application of U.S. Patent Application Serial No. 09/119,317, filed on July 20, 1998, now U.S. Patent No. 6,268,584, which was a divisional application of U.S. Patent Application Serial No. 09/010,673, filed on January 22, 1998, now U.S. Patent No. 5,993,554.--

In the claims:

Please amend the claims to read as follows (changes shown on attachment):

- B2
1. (Twice Amended) A direct material deposition method comprising the steps of:
- a. providing a powdered material that can be incited by a laser beam;
  - b. providing a laser nozzle assembly having multiple laser beams coupled with said powdered material from a set of powder nozzles directed to approximately a same location;
  - c. positioning a deposition substrate adjacent to laser deposition head outlets;
  - d. heating said powdered material on said deposition substrate with said laser beams; and
  - e. providing relative motion between said laser deposition head outlets and said deposition substrate.

- B3
3. (Twice Amended) The method of Claim 1, wherein said step of providing a laser nozzle assembly comprises providing a laser nozzle assembly having multiple laser beams focused on approximately a same location.

9. (Amended) A direct material deposition method comprising the steps of:

- 34
- a. providing a powdered material that can be incited by a laser beam;
  - b. providing a laser nozzle assembly having three or more laser beams coupled with said powdered material from a set of powder nozzles directed to approximately a same location;
  - c. positioning a deposition substrate adjacent to laser deposition head outlets;
  - d. heating said powdered material on said deposition substrate with said laser beams; and
  - e. providing relative motion between said laser deposition head outlets and said deposition substrate.

35

11. (Amended) The method of Claim 9, wherein said step of providing a laser nozzle assembly comprises providing a laser nozzle assembly having three or more laser beams focused on approximately a same location.